

## Attachment A, Section 2

## Semiconductor manufacturing and testing equipment and parts thereof

|    | HS Code | Description                                                                                                                                        | Comments         |
|----|---------|----------------------------------------------------------------------------------------------------------------------------------------------------|------------------|
| ex | 7017 10 | Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semiconductor wafers               | For Attachment B |
| ex | 8419 89 | Chemical vapor deposition apparatus for semiconductor production                                                                                   | For Attachment B |
| ex | 8419 90 | Parts of chemical vapor deposition apparatus for semiconductor production                                                                          | For Attachment B |
| ex | 8421 19 | Spin dryers for semiconductor wafer processing                                                                                                     |                  |
| ex | 8421 91 | Parts of spin dryers for semiconductor wafer processing                                                                                            |                  |
| ex | 8424 89 | Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process         |                  |
| ex | 8424 89 | Spraying appliances for etching, stripping or cleaning semiconductor wafers                                                                        |                  |
| ex | 8424 90 | Parts of spraying appliances for etching, stripping or cleaning semiconductor wafers                                                               |                  |
| ex | 8456 10 | Machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers          |                  |
| ex | 8456 91 | Apparatus for stripping or cleaning semiconductor wafers                                                                                           | For Attachment B |
|    | 8456 91 | Machines for dry-etching patterns on semiconductor materials                                                                                       |                  |
| ex | 8456 99 | Focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices                                    |                  |
| ex | 8456 99 | Laser cutters for cutting contacting tracks in semiconductor production by laser beam                                                              | For Attachment B |
| ex | 8464 10 | Machines for sawing monocrystal semiconductor boules into slices, or wafers into chips                                                             | For Attachment B |
| ex | 8464 20 | Grinding, polishing and lapping machines for processing of semiconductor wafers                                                                    |                  |
| ex | 8464 90 | Dicing machines for scribing or scoring semiconductor wafers                                                                                       |                  |
| ex | 8466 91 | Parts for machines for sawing monocrystal semiconductor boules into slices, or wafers into chips                                                   | For Attachment B |
| ex | 8466 91 | Parts of dicing machines for scribing or scoring semiconductor wafers                                                                              | For Attachment B |
| ex | 8466 91 | Parts of grinding, polishing and lapping machines for processing of semiconductor wafers                                                           |                  |
| ex | 8466 93 | Parts of focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices                           |                  |
| ex | 8466 93 | Parts of laser cutters for cutting contacting tracks in semiconductor production by laser beam                                                     | For Attachment B |
| ex | 8466 93 | Parts of machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers |                  |
| ex | 8456 93 | Parts of apparatus for stripping or cleaning semiconductor wafers                                                                                  | For Attachment B |
| ex | 8466 93 | Parts of machines for dry-etching patterns on semiconductor materials                                                                              |                  |
| ex | 8477 10 | Encapsulation equipment for assembly of semiconductors                                                                                             | For Attachment B |
| ex | 8477 90 | Parts of encapsulation equipment                                                                                                                   | For Attachment B |